MAXIMUM RATINGS

		MURS						
Rating	Symbol	105T3	110T3	115T3	120T3	140T3	160T3	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	50	100	150	200	400	600	٧
Average Rectified Forward Current	I _{F(AV)}	1.0 @ T _L = 155°C 2.0 @ T _L = 145°C 2.0			1.0 @ T _L 2.0 @ T _L	= 150°C = 125°C	Α	
Non-Repetitive Peak Surge Current, (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	I _{FSM}	40 35		5	Α			
Operating Junction Temperature	T _J	- 65 to +175			°C			

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

			MURS						
Rating		Symbol	105T3	110T3	115T3	120T3	140T3	160T3	Unit
Thermal Resistance, Junction-to-Lead	(T _L = 25°C)	$R_{\theta JL}$	JL 13				°C/W		
ELECTRICAL CHARACTERISTICS									

Maximum Instantaneous Forward Voltage (Note 1) $(i_F = 1.0 \text{ A}, T_J = 25^{\circ}\text{C})$ $(i_F = 1.0 \text{ A}, T_J = 150^{\circ}\text{C})$	v _F	0.875 0.71	1.25 1.05	V
Maximum Instantaneous Reverse Current (Note 1) (Rated DC Voltage, T _J = 25°C) (Rated DC Voltage, T _J = 150°C)	i _R	2.0 50	5.0 150	μΑ
Maximum Reverse Recovery Time $ \begin{aligned} (i_F = 1.0 \text{ A, di/dt} = 50 \text{ A/}\mu\text{s}) \\ (i_F = 0.5 \text{ A, i}_R = 1.0 \text{ A, I}_R \text{ to } 0.25 \text{ A}) \end{aligned} $	t _{rr}	35 25	75 50	ns
Maximum Forward Recovery Time (i _F = 1.0 A, di/dt = 100 A/μs, Rec. to 1.0 V)	t _{fr}	25	50	ns

^{1.} Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2.0%.

DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
MURS105T3		SMB	
MURS105T3G	U1A	SMB (Pb-Free)	
MURS110T3		SMB	
MURS110T3G	U1B	SMB (Pb-Free)	
MURS115T3		SMB	
MURS115T3G	U1C	SMB (Pb-Free)	OFOO Heite / Tana & Baal
MURS120T3		SMB	2500 Units / Tape & Reel
MURS120T3G	U1D	SMB (Pb-Free)	
MURS140T3		SMB	
MURS140T3G	U1G	SMB (Pb-Free)	
MURS160T3		SMB	
MURS160T3G	U1J	SMB (Pb-Free)	

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MURS105T3, MURS110T3, MURS115T3, MURS120T3

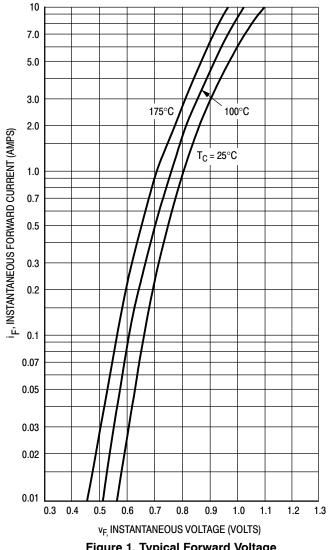


Figure 1. Typical Forward Voltage

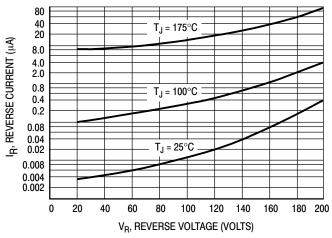


Figure 2. Typical Reverse Current*

*The curves shown are typical for the highest voltage device in the voltage grouping. Typical reverse current for lower voltage selections can be estimated from these same curves if applied V_R is sufficiently below rated V_R.

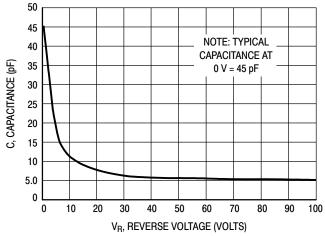


Figure 3. Typical Capacitance

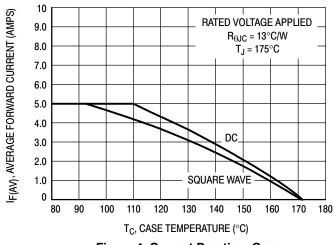


Figure 4. Current Derating, Case

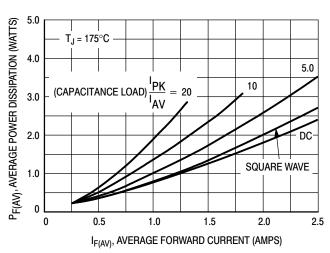
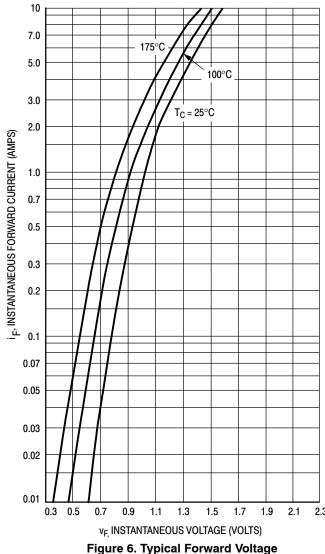


Figure 5. Power Dissipation

MURS140T3, MURS160T3



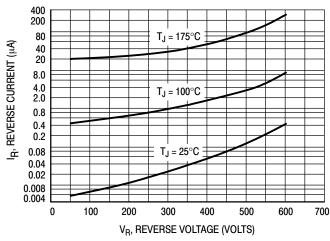


Figure 7. Typical Reverse Current*

*The curves shown are typical for the highest voltage device in the voltage grouping. Typical reverse current for lower voltage selections can be estimated from these same curves if applied V_B is sufficiently below rated V_R.

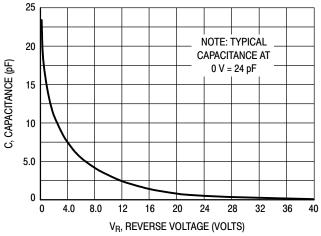


Figure 8. Typical Capacitance

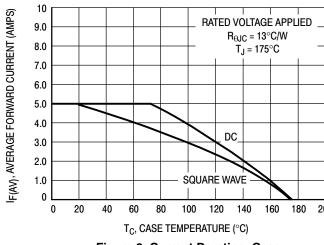


Figure 9. Current Derating, Case

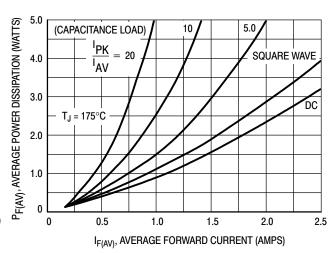
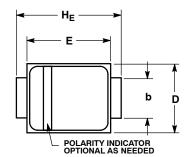


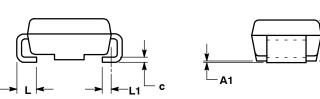
Figure 10. Power Dissipation

PACKAGE DIMENSIONS

SMB

CASE 403A-03 **ISSUE G**



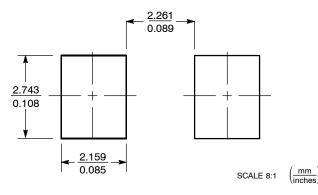


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
- 3. D DIMENSION SHALL BE MEASURED WITHIN DIMENSION P.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	1.90	2.13	2.45	0.075	0.084	0.096	
A1	0.05	0.10	0.20	0.002	0.004	0.008	
b	1.96	2.03	2.20	0.077	0.080	0.087	
С	0.15	0.23	0.31	0.006	0.009	0.012	
D	3.30	3.56	3.95	0.130	0.140	0.156	
E	4.06	4.32	4.60	0.160	0.170	0.181	
HE	5.21	5.44	5.60	0.205	0.214	0.220	
L	0.76	1.02	1.60	0.030	0.040	0.063	
L1	0.51 REF			0.020 REF			

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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